

Harvatek Surface Mount LED Data Sheet HT-F195 InGaN Series

Official Product	Product: HT-F195 InGaN Series	Data Sheet No.		
Tentative Product	******			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 1/20



DISCLAIMER	3
PRODUCT SPECIFICATIONS	4
ATTENTION: ELECTROSTATIC DISCHARGE (ESD) PROTECTION	4
LABEL SPECIFICATIONS	5
PRODUCT CHARACTERISTICS	9
ABSOLUTE MAXIMUM RATINGS	9
ELECTRO-OPTICAL CHARACTERISTICS	9
PACKAGE OUTLINE DIMENSION	10
RECOMMENDED SOLDERING PATTERN FOR REFLOW SOLDERING	10
CHARACTERISTIC CURVES	
RADIATION PATTERN	
PACKAGING	13
TAPE DIMENSION	13
REEL DIMENSION	14
Packing	15
DRY PACK	16
REFLOW SOLDERING	17
PRECAUTIONS	18
Reworking	18
CLEANING	18
RELIABILITY	19
REVISION HISTORY	20

Official Product	Product: HT-F195 InGaN Series	Data Sheet No.		
Tentative Product	******			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 2/20



DISCLAIMER

HARVATEK reserves the right to make changes without further notice to any products herein to improve reliability, function or design. HARVATEK does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under its patent rights, nor the rights of others.

LIFE SUPPORT POLICY

HARVATEK's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of HARVATEK or HARVATEK INTERNATIONAL. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

Official Product	Product: HT-F195 InGaN Series	Data Sheet No.		
Tentative Product	******	HT-F195 InGaN Series		
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 3/20



Product Specifications

Product	Emission Color	Technology	Test Current I _F (mA)	Luminous Intensity I _V (mcd)	Forward Voltage V _F (V)	Orderable Part Number
HT-F195NB	Blue	InGaN	20	90 typ	3.3 typ	HT-F195NB-ZZZZ
HT-F195NG	True Green	InGaN	20	160 typ	3.3 typ	HT-F195NG-ZZZZ
HT-F195TW	White	InGaN	20	250 typ	3.3 typ	HT-F195TW-ZZZZ

	Specification	Material	Quantity
Resin	Water clear	Epoxy resin	
Carrier tape	Per EIA 481-1A specs	Conductive black tape	4000pcs per reel
Reel	Per EIA 481-1A specs	Conductive black	
Label	HT standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	HT standard	Paper	

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and

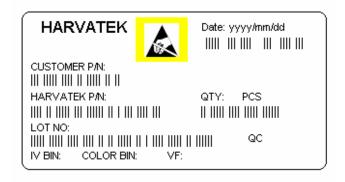
InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

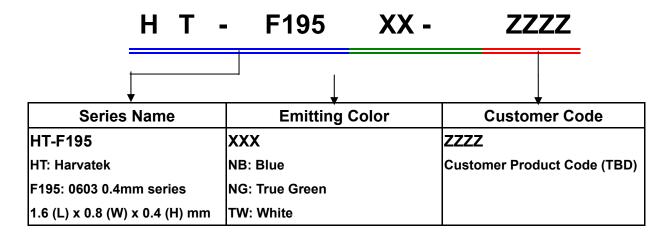
Official Product	Product: HT-F195 InGaN Series	Data Sheet No.		
Tentative Product	******			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 4/20



Label Specifications



Harvatek P/N:



Lot No.:

1 2 3 4 5 6 7 8 9 10 P 1 2 2 3 0 A - D T

Official Product	Product: HT-F195 InGaN Series	Data Sheet No.		
Tentative Product	*******			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 5/20



Code 1	Code 2	Code 3	Code 4, 5	Code 6, 7	Code 9	Code 10
	Mfg. Year	Mfg. Month	Mfg. Date	Lots	Resin Color	Packaging
		1: Jan.				
	Z: 2000	2: Feb.				
Internal	1: 2001			04-00	D: Diffused	
Tracing	2: 2002	9: Sep.	1~31/ (30)	01~99,	C: Clear	T: Tape & Reel
Code	3: 2003	A: Oct.		A,B,C	C: Clear	
		B: Nov.				
		C: Dec.				

Luminous Intensity (I_v) Bin:

Bin	Luminous Inten	sity Range (mcd)	Bin	Luminous Inter	nsity Range (mcd)
Dill	Minimum	Maximum	DIII	Minimum	Maximum
H1	2.8	3.6	H2	3.6	4.5
J1	4.5	5.7	J2	5.7	7.2
K1	7.2	9.0	K2	9.0	11.2
L1	11.2	14.2	L2	14.2	18.0
M1	18.0	22.5	M2	22.5	28.5
N1	28.5	36.0	N2	36.0	45.0
P1	45.0	57.0	P2	57.0	71.5
Q1	71.5	90.0	Q2	90.0	112.5
R1	112.5	142.0	R2	142.0	180.0
S 1	180.0	227.0	S2	227.0	285.0
T1	285.0	360.0	T2	360.0	450.0
U1	450.0	570.0	U2	570.0	715.0

@20mA / Ta=25° C, Tolerance: <u>+</u> 10%

Official Product	Product: HT-F195 InGaN Series	Data Sheet No.		
Tentative Product	********			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 6/20



Wavelength (λ_D) Bin:

	Wav	elength	Range (nm)			
Bin	True	Green	ВІ	Blue		
	(N	G)	(N	B)		
	Min Max		Min	Max		
-						
Α	515.0	520.0	460.0	464.0		
В	520.0	525.0	464.0	468.0		
С	525.0	530.0	468.0	472.0		
D	530.0	535.0	472.0	476.0		
E	535.0	540.0	476.0	480.0		
F			480.0	485.0		
Н						
J						

@20mA / Ta=25° C, Tolerance: <u>+</u> 0.5nm

Forward Voltage (V_F) Bin:

Color	Bin Code	Spec. Range
	G8	2.7-2.9 V
Dive (ND)	H7	2.9-3.1 V
Blue (NB)	Н8	3.1-3.3 V
Green (NG)	J7	3.3-3.5 V
White (TW)	J8	3.5-3.7 V
	K7	3.7-3.9 V

@20mA / Ta=25°C, Tolerance: + 0.05 V

Official Product	Product: HT-F195 InGaN Series	Data Sheet No.					
Tentative Product	*******	*******					
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 7/20			



Chromaticity Bin (for TW only):

	Rank A0					
Х	0.280	0.264	0.283	0.296		
У	0.248	0.267	0.305	0.276		

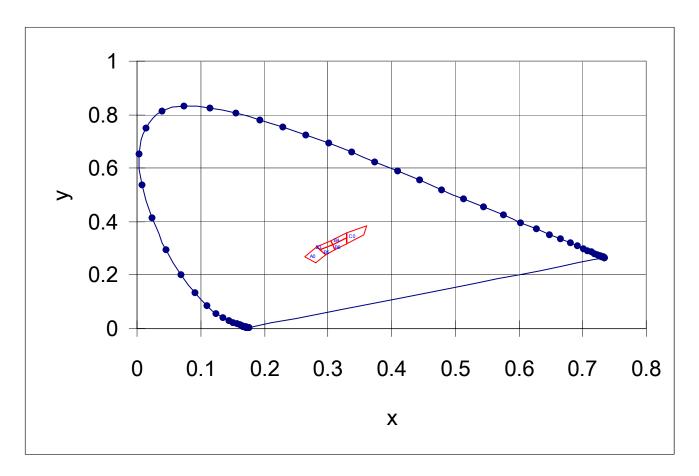
	Rank B3					
Х	0.287	0.283	0.304	0.307		
У	0.295	0.305	0.330	0.315		

	Rank B4					
Х	0.307	0.304	0.330	0.330		
У	0.315	0.330	0.360	0.339		

	Rank C0					
Х	0.330	0.330	0.361	0.356		
У	0.318	0.360	0.385	0.351		

	Rank B5					
Х	0.296	0.287	0.307	0.311		
У	0.276	0.295	0.315	0.294		

	Rank B6						
Х	0.311	0.307	0.330	0.330			
У	0.294	0.315	0.339	0.318			



@20mA / Ta=25°C, Tolerance: + 0.01

Official Product	Product: HT-F195 InGaN Series	Data Sheet No.					
Tentative Product	*******	*******					
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 8/20			



Product Characteristics

Absolute Maximum Ratings

Product	Emission Color	P _d (mW)	I _F (mA)	I _{FP} * (mA)	V _R (V)	T _{OP} (°C)	T _{ST} (°C)
HT-F195NB	Blue						
HT-F195NG	True Green	117	30	120	5	-40~+100	-40~+100
HT-F195TW	White						

^{*} Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width

Electro-Optical Characteristics

 $(T_a = 25 \circ C)$

			V _F (V)		λ(nm)			I* _∨ (mcd)	
Product	Emission Color	I _F (mA)	typ	max	λ D	λ P	Δλ	min	typ
HT-F195NB	Blue	20	3.3	3.9	470	468	40	36	90
HT-F195NG	True Green	20	3.3	3.9	527	520	40	90	160
HT-F195TW	White	20	3.3	3.9	X=0.29 Y=0.31	-	-	140	250

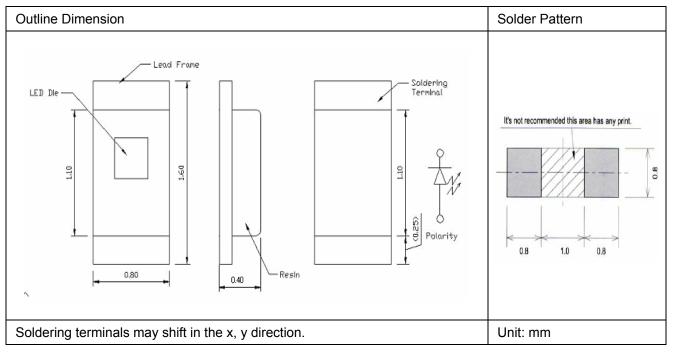
^{*} Per NIST standards

Official Product	Product: HT-F195 InGaN Series	Data Sheet No.		
Tentative Product	********	HT-F195 InGaN Series		
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 9/20



Package Outline Dimension Recommended Soldering Pattern for Reflow Soldering

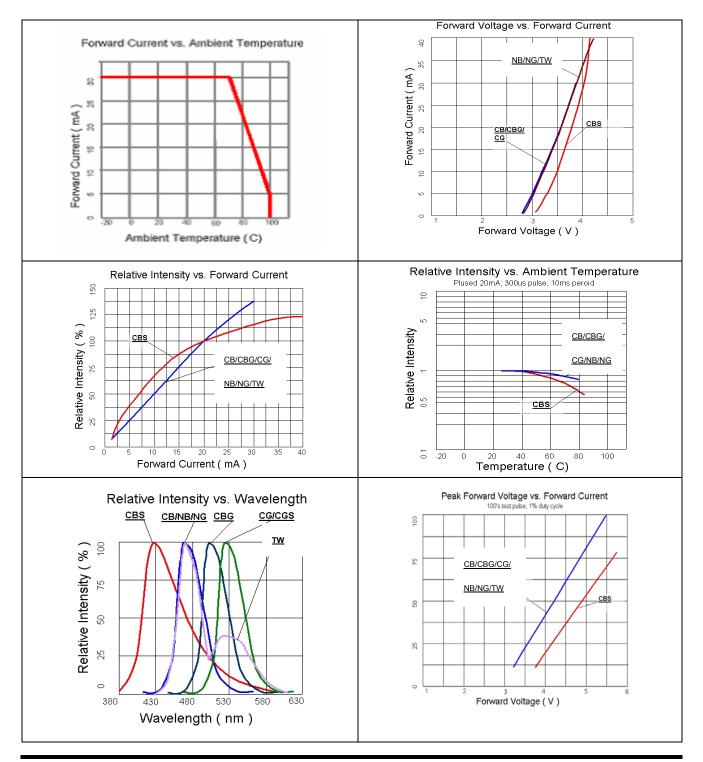
Unit: mm Tolerance: +/-0.1



Official Product	Product: HT-F195 InGaN Series			Data Sheet No.
Tentative Product	*******			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 10/20



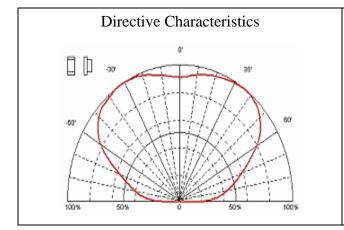
Characteristic Curves

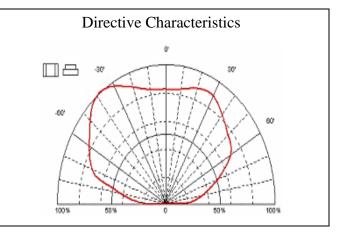


Official Product	Product: HT-F195 InGaN Series			Data Sheet No.
Tentative Product	******			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 11/20



Radiation Pattern



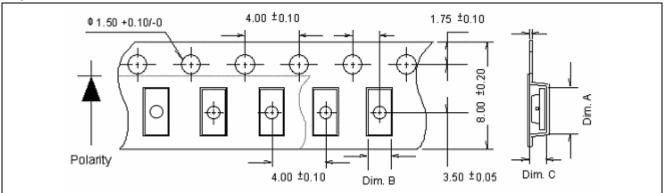


Official Product	Product: HT-F195 InGaN Series			Data Sheet No.
Tentative Product	*******			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 12/20



Packaging

Tape Dimension



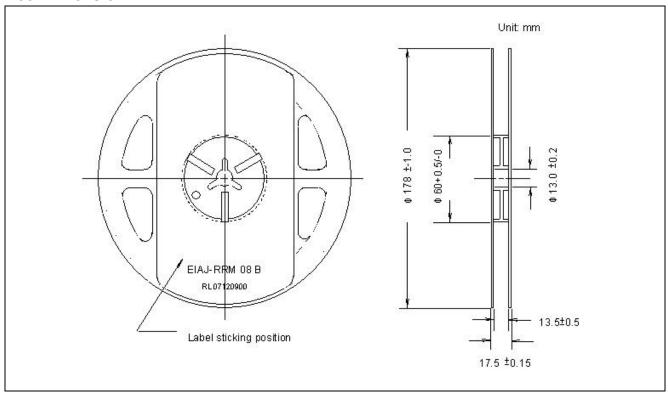
Part No.	Dim. A	Dim. B	Dim. C	Q'ty/Reel
HT-F195	1.75±0.10	0.90±0.10	0.60±0.10	4K

Unit: mm

				5
Official Product	Product: HT-F195 InGaN Series			Data Sheet No.
Tentative Product	*******			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 13/20



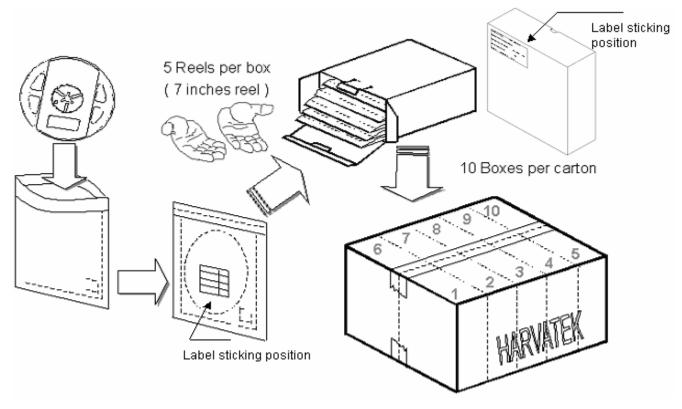
Reel Dimension



Official Product	Product: HT-F195 InGaN Series			Data Sheet No.
Tentative Product	******			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 14/20



Packing



5 boxes per carton is available depending on shipment quantity.

	Specification	Material	Quantity
Carrier tape	Per EIA 481-1A specs	Conductive black tape	4000pcs per reel
Reel	Per EIA 481-1A specs	Conductive black	
Label	HT standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	HT standard	Paper	Non-specified

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Official Product	Product: HT-F195 InGaN Series			Data Sheet No.
Tentative Product	******			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 15/20

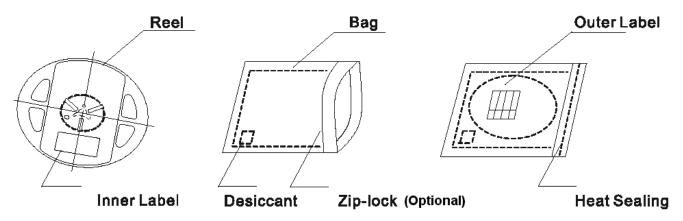


Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



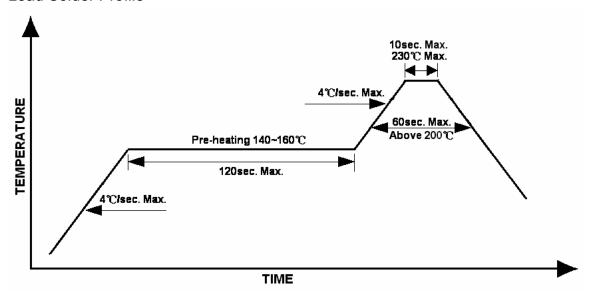
Official Product	Product: HT-F195 InGaN Series			Data Sheet No.
Tentative Product	******			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 16/20



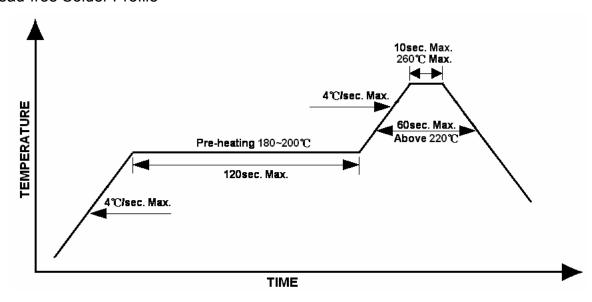
Reflow Soldering

- Recommended tin glue specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

Lead Solder Profile



Lead-free Solder Profile



Official Product	Product: HT-F195 InGaN Series			Data Sheet No.
Tentative Product	******			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 17/20



Precautions

- 1. Avoid exposure to moisture at all times during transportation or storage.
- 2. Anti-Static precaution must be taken when handling GaN, InGaN, and AllnGaP products.
- 3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
- 4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
- 5. Avoid direct contact with the surface through which the LED emits light.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

Official Product	Product: HT-F195 InGaN Series			Data Sheet No.
Tentative Product	*******			HT-F195 InGaN Series
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 18/20



Reliability

Item	Frequency/ lots/ samples/ failures	Standards Reference	Conditions
Precondition	For all reliability monitoring tests according to JEDEC Level 2	J-STD-020	1.) Baking at 85°C for 24hrs 2.) Moisture storage at 85°C/ 60% R.H. for 168hrs
Solderability	1Q/ 1/ 22/ 0	JESD22-B102-B And CNS-5068	Accelerated aging 155°C/ 24hrs Tinning speed: 2.5+0.5cm/s Tinning: A: 215°C/ 3+1s or B: 260°C/ 10+1s
Resistance to soldering heat		CNS-5067	Dipping soldering terminal only Soldering bath temperature A: 260+/-5°C; 10+/-1s B: 350+/-10°C; 3+/-0.5s
Operating life test	1Q/ 1/ 40/ 0	CNS-11829	1.) Precondition: 85°C baking for 24hrs 85°C/ 60%R.H. for 168hrs 2.) Tamb25°C; IF=20mA; duration 1000hrs
High humidity, high temperature bias	1Q/ 1/ 45/ 0	JESD-A101-B	Tamb: 85°C Humidity: 85% R.H., IF=5mA Duration: 1000hrs
High temperature bias	1Q/ 1/ 20	HT specs.	Tamb: 55°C IF=20mA Duration: 1000hrs
Pulse life test	1Q/ 1/ 40/ 0		Tamb25°C, If=20mA,, Ip=100mA, Duty cycle=0.125 (tp=125µs,T=1sec) Duration 500hrs)
Temperature cycle	1Q/ 1/ 76/ 0	JESD-A104-A IEC 68-2-14, Nb	A cycle: -40 degree C 15min; +85 degree C 15min Thermal steady within 5 min 300 cycles 2 chamber/ Air-to-air type
High humidity storage test	1Q/ 1/ 40/ 0	CNS-6117	60+3°C 90+5/-10% R.H. for 500hrs
High temperature storage test	1Q/ 1/ 40/ 0	CNS-554	100+10°C for 500hrs
Low temperature storage test	1Q/ 1/ 40/ 0	CNS-6118	-40+5°C for 500hrs

Official Product	Product: HT-F195 InGaN Series	Data Sheet No.		
Tentative Product	********	HT-F195 InGaN Series		
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 19/20



Revision History

Changes since last revision		age	Version No.	Revision Date
New format			1.0	07-15-2005
Correct type in packaging		13	1.01	10-12-2005

Official Product	Product: HT-F195 InGaN Series	Data Sheet No.		
Tentative Product	********	HT-F195 InGaN Series		
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		Oct. 12, 2005	Version of 1.01	Page 20/20

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Harvatek:

HT-F195NB-5496 HT-F195NG-5501 HT-F195TW-5497